



SesameLASERPlasma™  
The Best Quality/Price ratio  
of the market

## CHARACTERISTICS

### SLP500

- Dimension: D: 840 mm / W: 535 mm / H: 900 mm
- Weight: 120 kg
- Power supply: 110-250VAC / 50/60 Hz / Max 700W
- Working area: 375 x 375 mm

### SLP500+

- Dimension: D: 870 mm / W: 710 mm / H: 1870 mm
- Weight: 350 kg
- Power supply: 110-250VAC / 50/60 Hz / Max 800W
- Working area: 375 x 375 mm

### SLP1000

- Dimension: D: 1075 mm / W: 1340 mm / H: 1900 mm
- Weight: up to 600 kg
- Power supply: 110-250VAC / 50/60 Hz / 1000W
- Working area: 600 x 750 mm

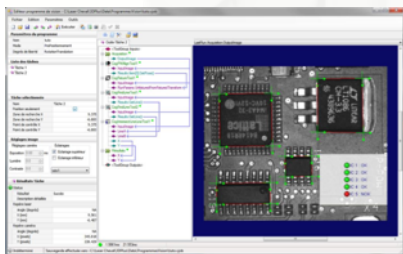


**UP-GRADE / TRADE-IN**  
Of your old S500 and S1000



## OPTIONS

- Automatic Samples recognition
- Table with Screen arm
- Cross-section capabilities
- Multi-pulse width LASER source
- Direct view through Galvo-Head Camera
- Programmable X-Y table
- Fast Cooler
  - Enhanced cooled air blow off helps optimize recipes more efficiently and protects delicate components
  - Improve efficiency of Cross section on PCB with thick Cu materials



ISLP\_General\_R2 - Non-contractual photographs



ASIA AMERICA EUROPE

iSLaser™

iSLP™ IC PreDCAP

iSLP™ IC PreDCAP



## APPLICATIONS 2019

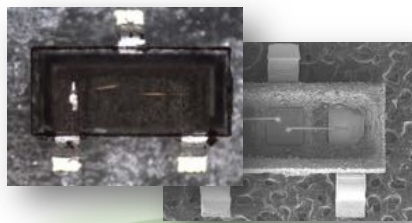
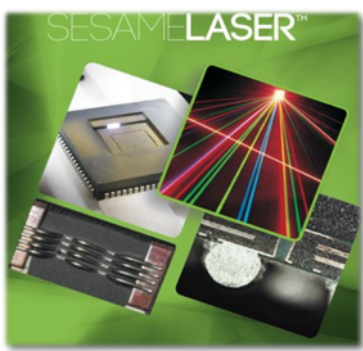
- Pre-cavity before ACIDS or Plasma
- Cross-section
- Surface Activation Gasket Maker
- IC extraction from PCB
  - Ablation of Si, Al<sub>2</sub>O<sub>3</sub> ...
  - SIMS extraction from wafer



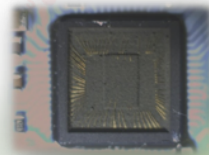
A GREEN WORLD WITH DC - LESS ACID - LESS CF4 - AND ALL FOR YOUR FUTURE IC PACKAGES

ASIA AMERICA EUROPE

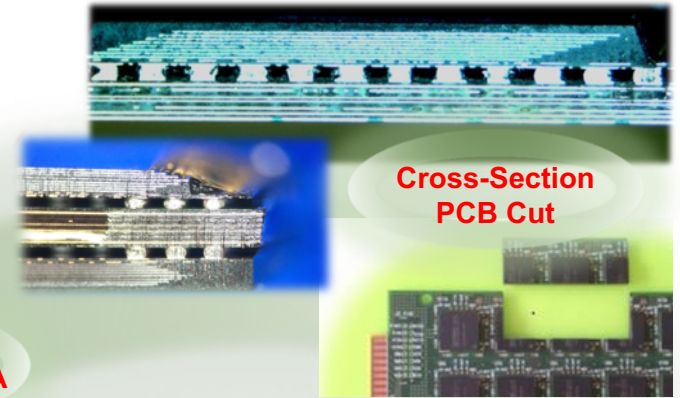




**Pocket before  
ACID or PLASMA ...**



**... and after  
ACID or PLASMA**



**Cross-Section  
PCB Cut**



**iSLP500**

**The Best Quality/Price  
Ratio of the market**



**iSLP500+**

**Add Automatic safety door**



**MAIN FEATURES**

- 10W 20W 30W IR Fiber LASER
- 3:1 tool: Decapsulation, marking, cross section
- Laser ablation area up to 170x170mm
- Atmospheric Plasma Assisted™ (\*1)
- Compatible with Al, Au, Cu, Cu/ , Ag wires
- Quick assisted focus with its lateral camera
- Real time vision during ablation with wide choice of FOV
- Easy to use with an intuitive software
- Precise decapsulation using imported images
- Small footprint and easy to move
- Design your own gasket
- Z Motorized in Standard
- Fast upgrade on site



**Acid Gasket  
Maker**

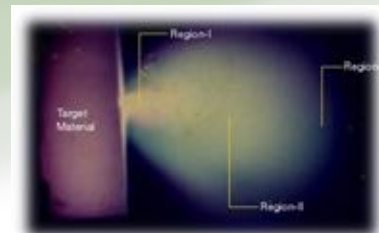
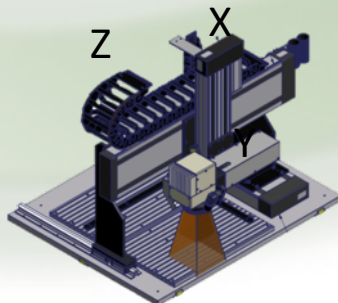
**OPTIONS**

- Table with Screen arm
- Cross-section capabilities
- Multi-pulse width LASER source
- Direct view through Galvo-Head Camera
- Cooler blast
- Programmable X-Y table



**iSLP1000**

**Add X or/and Y Motorized Axis**



**iSLP™ ... Sublimation end Plasma**



**MAIN CHARACTERISTICS**

- Atmospheric Plasma Assisted (PATENTED\*). Avoid oxidation of sensitive material like Cu and Ag by
- Control of your external Suction Unit
  - Automatic Start & Stop
  - Adjustable delay

**EXTENSION MODULE**

(\* ) PATENTED (CNES/DC) LASER PLASMA TECHNOLOGY

CHINA: CN200780050958 / USA: 8,555,728 B2 / KOREA: 10-2009-7015599 / MALAYSIA: 20092729 / EUROPE: 2095410 A1